



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20170928005
Qualification of Hefei Tongfu Microelectronic Co. Ltd (HFTF) as
additional Assembly and Test Site for Select Devices
Change Notification / Sample Request

Date: October 02, 2017
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20170928005
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AUP1G125DCKR	null
SN74CBTLV1G125DCKR	null
SN74LVC1G08DCKR	null
SN74LVC1G125DCKR	null
SN74LVC1G126DCKR	null
SN74LVC1G175DCKR	null
SN74LVC1G32DCKR	null
SN74LVC1G97DCKR	null
SN74LVC2G14DCKR	null
SN74AHC1G00DCKR	null
SN74AHC1G00DCKT	null
SN74AHC1G02DCKR	null
SN74AHC1G04DCKR	null
SN74AHC1G08DCKR	null
SN74AHC1G08DCKT	null
SN74AHC1G09DCKR	null
SN74AHC1G125DCKR	null
SN74AHC1G126DCKR	null
SN74AHC1G126DCKT	null
SN74AHC1G14DCKR	null
SN74AHC1G14DCKT	null
SN74AHC1G32DCKR	null
SN74AHC1G32DCKT	null
SN74AHC1G86DCKR	null
SN74AHC1GU04DCKR	null
SN74AHCT1G00DCKR	null
SN74AHCT1G00DCKT	null
SN74AHCT1G04DCKR	null
SN74AHCT1G04DCKT	null
SN74AHCT1G125DCKR	null
SN74AHCT1G126DCKR	null
SN74AHCT1G14DCKR	null
SN74CB3T1G125DCKR	null
SN74LV1T04DCKR	null
SN74LV1T125DCKR	null
SN74LV1T126DCKR	null
SN74LV1T34DCKR	null
SN74LVC1G00DCKR	null
SN74LVC1G02DCKR	null
SN74LVC1G0832DCKT	null
SN74LVC1G08DCKT	null
SN74LVC1G11DCKR	null
SN74LVC1G132DCKR	null
SN74LVC1G14DCKR	null
SN74LVC1G175DCKT	null
SN74LVC1G17DCKR	null
SN74LVC1G17DCKT	null
SN74LVC1G18DCKR	null
SN74LVC1G19DCKR	null
SN74LVC1G240DCKR	null
SN74LVC1G27DCKR	null
SN74LVC1G3157DCKR	null
SN74LVC1G3208DCKR	null
SN74LVC1G32DCKT	null
SN74LVC1G332DCKR	null
SN74LVC1G34DCKR	null
SN74LVC1G373DCKR	null

SN74LVC1G374DCKR	null
SN74LVC1G386DCKR	null
SN74LVC1G38DCKR	null
SN74LVC1G38DCKT	null
SN74LVC1G57DCKR	null
SN74LVC1G58DCKR	null
SN74LVC1G66DCKR	null
SN74LVC1G66DCKT	null
SN74LVC1G79DCKR	null
SN74LVC1G80DCKR	null
SN74LVC1G80DCKT	null
SN74LVC1G86DCKR	null
SN74LVC1G98DCKR	null
SN74LVC1G98DCKT	null
SN74LVC1GU04DCKR	null
SN74LVC1GU04DCKT	null
SN74LVC1GX04DCKT	null
SN74LVC2G04DCKR	null
SN74LVC2G04DCKT	null
SN74LVC2G07DCKR	null
SN74LVC2G07DCKT	null
SN74LVC2G14DCKT	null
SN74LVC2G17DCKR	null
SN74LVC2G17DCKT	null
SN74LVC2G34DCKR	null
SN74LVC2GU04DCKR	null
TS5A3157DCKR	null
SN74LVC1G10DCKR	null
SN74LVC2G06DCKR	null
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SN74AHC1GU04DCKT	null
SN74AHCT1G02DCKT	null
SN74AHCT1G126DCKT	null
SN74AHCT1G14DCKT	null
SN74AHCT1G32DCKT	null
SN74AHCT1G86DCKT	null
SN74CBT1G384DCKT	null
SN74LVC1G125DCKT	null
SN74LVC1G3208DCKT	null
SN74LVC1G79DCKT	null


Technical details of this Product Change follow on the next page(s).

PCN Number:	20170928005		PCN Date:	Oct. 2, 2017													
Title:	Qualification of Hefei Tongfu Microelectronic Co. Ltd (HFTF) as additional Assembly and Test Site for Select Devices																
Customer Contact:	PCN Manager	Dept:	Quality Services														
Proposed 1st Ship Date:	Jan. 2, 2018		Estimated Sample Availability:	Date provided at sample request													
Change Type:																	
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process												
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site												
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials												
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments is pleased to announce the Qualification of Hefei Tongfu Microelectronic Co. Ltd (HFTF) as additional Assembly and Test Site for Select Devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>NFME</td> <td>NFM</td> <td>CHN</td> <td>Chongchuan</td> </tr> <tr> <td>HFTF</td> <td>HFT</td> <td>CHN</td> <td>Hefei</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	NFME	NFM	CHN	Chongchuan	HFTF	HFT	CHN	Hefei
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City														
NFME	NFM	CHN	Chongchuan														
HFTF	HFT	CHN	Hefei														
Material Differences:																	
<table border="1"> <thead> <tr> <th></th> <th>NFME</th> <th>HFTF</th> </tr> </thead> <tbody> <tr> <td>Lead finish</td> <td>NiPdAu</td> <td>Matte Sn</td> </tr> <tr> <td>Mold compound</td> <td>R-07</td> <td>R-27</td> </tr> </tbody> </table>							NFME	HFTF	Lead finish	NiPdAu	Matte Sn	Mold compound	R-07	R-27			
	NFME	HFTF															
Lead finish	NiPdAu	Matte Sn															
Mold compound	R-07	R-27															
Upon expiration of this PCN, TI will combine lead free solutions in a single <u>standard part number</u> , for example; <u>SN74AHC1G00DCKR</u> – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. <u>SN74AHC1G00DCKRG4.</u>																	
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																	
Reason for Change:																	
Continuity of supply.																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Anticipated impact on Material Declaration																	
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.														
Changes to product identification resulting from this PCN:																	

Assembly Site			
NFME	Assembly Site Origin (22L)	ASO: NFM	ECAT: G4
HFTF	Assembly Site Origin (22L)	ASO: HFT	ECAT: G3

Sample product shipping label (not actual product label)

ECAT: G4 = NiPdAu
ECAT: G3 = Matte Sn

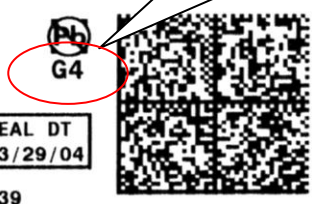


MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: NFME = E, HFTF = J

Product Affected: Group 1

SN74AHC1G00DCKR	SN74AHCT1G32DCKR	SN74LVC1G10DCKR	SN74LVC1G58DCKR
SN74AHC1G00DCKT	SN74AHCT1G32DCKT	SN74LVC1G11DCKR	SN74LVC1G66DCKR
SN74AHC1G02DCKR	SN74AHCT1G86DCKR	SN74LVC1G125DCKR	SN74LVC1G66DCKT
SN74AHC1G02DCKT	SN74AHCT1G86DCKT	SN74LVC1G125DCKT	SN74LVC1G79DCKR
SN74AHC1G04DCKR	SN74AUP1G125DCKR	SN74LVC1G126DCKR	SN74LVC1G79DCKT
SN74AHC1G04DCKT	SN74AUP1G125DCKT	SN74LVC1G126DCKT	SN74LVC1G80DCKR
SN74AHC1G08DCKR	SN74CB3T1G125DCKR	SN74LVC1G132DCKR	SN74LVC1G80DCKT
SN74AHC1G08DCKT	SN74CBT1G125DCKR	SN74LVC1G132DCKT	SN74LVC1G86DCKR
SN74AHC1G09DCKR	SN74CBT1G125DCKT	SN74LVC1G14DCKR	SN74LVC1G86DCKT
SN74AHC1G125DCKR	SN74CBT1G384DCKR	SN74LVC1G14DCKT	SN74LVC1G97DCKR
SN74AHC1G125DCKT	SN74CBT1G384DCKT	SN74LVC1G175DCKR	SN74LVC1G97DCKT
SN74AHC1G126DCKR	SN74CBTD1G125DCKR	SN74LVC1G175DCKT	SN74LVC1G98DCKR
SN74AHC1G126DCKT	SN74CBTD1G125DCKT	SN74LVC1G17DCKR	SN74LVC1G98DCKT
SN74AHC1G14DCKR	SN74CBTD1G384DCKR	SN74LVC1G17DCKT	SN74LVC1GU04DCKR
SN74AHC1G14DCKT	SN74CBTD1G384DCKT	SN74LVC1G18DCKR	SN74LVC1GU04DCKT
SN74AHC1G32DCKR	SN74CBTLV1G125DCKR	SN74LVC1G19DCKR	SN74LVC1GX04DCKR
SN74AHC1G32DCKT	SN74LV1T00DCKR	SN74LVC1G240DCKR	SN74LVC1GX04DCKT
SN74AHC1G86DCKR	SN74LV1T02DCKR	SN74LVC1G240DCKT	SN74LVC2G04DCKR
SN74AHC1G86DCKT	SN74LV1T04DCKR	SN74LVC1G27DCKR	SN74LVC2G04DCKT
SN74AHC1GU04DCKR	SN74LV1T08DCKR	SN74LVC1G3157DCKR	SN74LVC2G06DCKR
SN74AHC1GU04DCKT	SN74LV1T125DCKR	SN74LVC1G3208DCKR	SN74LVC2G07DCKR
SN74AHCT1G00DCKR	SN74LV1T126DCKR	SN74LVC1G3208DCKT	SN74LVC2G07DCKT
SN74AHCT1G00DCKT	SN74LV1T32DCKR	SN74LVC1G32DCKR	SN74LVC2G14DCKR
SN74AHCT1G02DCKR	SN74LV1T34DCKR	SN74LVC1G32DCKT	SN74LVC2G14DCKT
SN74AHCT1G02DCKT	SN74LV1T86DCKR	SN74LVC1G332DCKR	SN74LVC2G17DCKR
SN74AHCT1G04DCKR	SN74LVC1G00DCKR	SN74LVC1G34DCKR	SN74LVC2G17DCKT
SN74AHCT1G04DCKT	SN74LVC1G00DCKT	SN74LVC1G34DCKT	SN74LVC2G34DCKR

SN74AHCT1G125DCKR	SN74LVC1G02DCKR	SN74LVC1G373DCKR	SN74LVC2GU04DCKR
SN74AHCT1G125DCKT	SN74LVC1G02DCKT	SN74LVC1G374DCKR	SN74LVC2GU04DCKT
SN74AHCT1G126DCKR	SN74LVC1G0832DCKR	SN74LVC1G386DCKR	TS5A1066DCKR
SN74AHCT1G126DCKT	SN74LVC1G0832DCKT	SN74LVC1G38DCKR	TS5A3157DCKR
SN74AHCT1G14DCKR	SN74LVC1G08DCKR	SN74LVC1G38DCKT	
SN74AHCT1G14DCKT	SN74LVC1G08DCKT	SN74LVC1G57DCKR	

Qualification Report
HFTF SOT: DCK Assy Site Qualification
Approve Date 26-Sep-2017

Product Attributes

Attributes	Qual Device: SN74AHC1G126DCKR	Qual Device: SN74CBT1G384DCKR	Qual Device: SN74LVC1G17DCKR	Qual Device: SN74LVC2G04DCKR
Assembly Site	HFTF	HFTF	HFTF	HFTF
Package Family	SC70	SC70	SC70	SC70
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	SFAB	FFAB	FFAB
Wafer Process	EPIC1S1	EPIC1ZS	A3C10TPI/50B10.13_BO PO2	ASL3C

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL1-260C: SN74CBT1G384DCKR, SN74AHC1G126DCKR, SN74LVC2G04DCKR, SN74LVC1G17DCKR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN74AHC1G126DCKR	Qual Device: SN74CBT1G384DCKR
AC	Autoclave 121C	96 Hours	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0
FLAM	Flammability (IEC 695-2-2)	--	-	-
FLAM	Flammability (UL 94V-0)	--	-	-
FLAM	Flammability (UL-1694)	--	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-
HTOL	Life Test, 150C	300 Hours	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	1/77/0	1/77/0
LI	Lead Fatigue	Leads	-	-
LI	Lead Pull to Destruction	Leads	-	-
PD	Physical Dimensions	--	-	-

SD	Solderability	Pb	-	-
SD	Solderability	Pb Free	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	1/77/0
WBP	Bond Pull	Wires	1/76/0	1/76/0
WBS	Ball Bond Shear	--	1/76/0	1/76/0

Type	Test Name / Condition	Duration	Qual Device: SN74LVC1G17DCKR	Qual Device: SN74LVC2G04DCKR
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	3/90/0
FLAM	Flammability (IEC 695-2-2)	--	-	-
FLAM	Flammability (UL 94V-0)	--	3/15/0	3/15/0
FLAM	Flammability (UL-1694)	--	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0
HTOL	Life Test, 150C	300 Hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	3/231/0
LI	Lead Fatigue	Leads	3/66/0	3/66/0
LI	Lead Pull to Destruction	Leads	3/27/0	3/27/0
PD	Physical Dimensions	--	-	-
SD	Solderability	Pb	3/66/0	3/66/0
SD	Solderability	Pb Free	3/66/0	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	--	3/228/0	3/228/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com